

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	73	(murakami-keiichi).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2007/12/15 00:34
S2	4	(murakami-keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2008/02/21 17:59
S3	4	("20050258522" "20060037193" "20060115582" "6739040"). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/21 18:09
S4	5	("3956041" "5057372" "5344893" "5346750" "6376053").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/23 22:24
S5	6	("3989767" "4504607" "4752499" "5021472" "5055321" "5137936").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/23 22:37
S6	57	("5055321").URPN.	USPAT	OR	OFF	2008/02/23 22:45
S7	12	("4752499" "5021472" "5055321" "5344893" "5447996" "5519177" "5589255" "5688583" "5741575" "5795618" "5921472" "6010768").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/23 23:12
S8	8	("6248428").URPN.	USPAT	OR	OFF	2008/02/23 23:13
S9	202	(pcb or ((circuit or wiring) adj board)) and (press\$3 with resin) and (cur\$3 with resin) and (polish\$3 with resin)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/23 23:17
S10	101	(pcb or ((circuit or wiring) adj board)) and (press\$3 with resin) and (cur\$3 with resin) same (polish\$3 with resin)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/23 23:17
S11	15	(pcb or ((circuit or wiring) adj board)) and (press\$3 with resin) same (cur\$3 with resin) same (polish\$3 with resin)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/23 23:17
S12	14	(pcb or ((circuit or wiring) adj board)) and (press\$3 with resin) and (polish\$3 with resin) and pressing adj plate	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:42

S15	18	(pcb or ((circuit or wiring) adj board)) and (press\$3 with prepreg) and (pressing adj plate)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:48
S16	8	("3884771").URPN.	USPAT	OR	OFF	2008/02/24 22:50
S17	1	(pcb or ((circuit or wiring) adj board)) and (press\$3 with heat \$3) and (pressing adj plate) near4 nickel	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:52
S21	504	(pcb or ((circuit or wiring) adj board)) and (press\$3 with heat \$3 with prepreg) with (laminat \$3)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:54
S22	197	(pcb or ((circuit or wiring) adj board)) and (press\$3 with heat \$3 with prepreg) with (laminat \$3) and nickel	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:55
S23	18	(pcb or ((circuit or wiring) adj board)) and (press\$3 with heat \$3 with nickel) with (laminat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 23:03
S24	105	(pcb or ((circuit or wiring) adj board)) and (press\$3 with heat \$3 with nickel)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 23:03
S25	6	("4541894" "5450290" "5484647" "5525402" "5600103" "5766670").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/24 23:10
S26	45	(pcb or ((circuit or wiring) adj board)) and ((press\$3 with heat \$3) same (nickel near2 (foil or plate or sheet)))	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 23:15
S27	12	(pcb or ((circuit or wiring) adj board)) and ((press\$3 near6 heat\$3) with (nickel near2 (foil or plate or sheet)))	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 23:32
S29	32	(29/847,830,831,846).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin) and (polish\$3 with resin)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:20
S32	13	(29/847,830,831,846).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:24
S34	13	(29/847,830,831,846).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:26

S35	1	(156/295,285).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:30
S36	10	(174/255,258).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:30
S37	2	(257/678,688).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:32
S38	4	(murakami-keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2008/02/28 11:59
S39	4	("20050258522" "20060037193" "20060115582" "6739040").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/28 12:34
S40	12	("4574371" "4752499" "4927983" "5021472" "5055321" "5227012" "5344893" "5447996" "5519177" "5589255" "5688583" "5741575").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/01 23:18
S41	14	("6010768").URPN.	USPAT	OR	OFF	2008/03/01 23:18
S42	4	(murakami-keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2008/03/01 23:19
S43	13	(29/847,830,831,846).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/03/01 23:20
S44	1	(156/295,285).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/03/01 23:20

S45	2	(257/678,688).ccls. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/03/01 23:20
S46	1	("6268648").PN.	USPAT; USOCR	OR	OFF	2008/03/01 23:21
S47	1	("5574309").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/01 23:21
S48	29	("6268648").URPN.	USPAT	OR	OFF	2008/03/01 23:21
S49	2	("6010768" "6268648").PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	ON	2009/02/01 13:25
S50	4	(murakami-keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	ON	2009/02/02 00:04
S51	15	(29/847,830,831,846).ccls. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2009/02/02 00:07
S52	1	(156/295,285).ccls. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2009/02/02 00:09
S53	2	(257/678,688).ccls. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2009/02/02 00:09
S54	4	resin with ((non adj (cure or cured or curable or curing)) near3 temperature) with (range or between or from or window)	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/17 11:41
S55	8	(epoxy or resin or resinous or resinous) same ((non adj (cure or cured or curable or curing)) near3 temperature) same (range or between or from or window)	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/17 11:43

S56	10	(murakami near keichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/18 00:52
S57	16	(29/847,830,831,846).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/18 00:57
S58	1	(156/295,285).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/18 00:58
S59	2	(257/678,688).cds. and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit\$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/18 01:00
S60	45	(resin with temperature with press\$3) and (pcb or ((circuit or wiring) adj board)) and (press\$3 with resin with (circuit \$4 or wiring or conductor or trace or line)) and (polish\$3 with resin) and cur\$3	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/18 01:02

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